

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MITCHELL CURIEL	07/25/2016
HUAN GIM CHAN	07/25/2016
WAN FOONG KHO	07/21/2016
RECEIVING PARTY DATA	
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Street Address:	6501 WILLIAM CANNON DRIVE WEST
City:	AUSTIN
State/Country:	TEXAS
Postal Code:	78735
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15221372
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ATTORNEY DOCKET NUMBER:	038.0683
NAME OF SUBMITTER:	JUSTIN J. LEACH
SIGNATURE:	/JUSTIN J. LEACH/
DATE SIGNED:	07/27/2016
Total Attachments: 3	
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source=20160727_Assignment_MT13521ZK-US01_038-0683#page3.tif	

SOLE ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, I, as a below-named Assignor, hereby sell, assign, and transfer the entire and exclusive right, title, and interest in the following to **FREESCALE SEMICONDUCTOR, INC.**, having a place of business at 6501 William Cannon Drive, Austin, TX 78735, USA, its successors, assigns, and legal representatives, including any nominees (collectively "the Assignee"):

(1) my invention relating to "**METHODS FOR REPACKAGING COPPER WIRE-BONDED MICROELECTRONIC DIE**" for which the following patent application(s) has/have been filed (I hereby authorize and request my/our attorneys associated with U.S. Patent & Trademark Office Customer Number 23125 to insert below the filing date and application number of the U.S. application when known):

<u>Country</u>	<u>Application No.</u>	<u>Filing Date (mm/dd/yyyy)</u>	<u>Claims Priority of</u>
US	15/221,372	July 27, 2016	N/A

(2) the foregoing application(s) and all other United States, foreign and international patent applications associated therewith, based thereon, or claiming priority there from including, but not limited to, any and all provisionals, non-provisionals, divisions, continuations, continuations-in-part, re-examinations, reissues, and extensions thereof, and

(3) the right to claim priority thereto, and the entire and exclusive right, title, and interest in and to any and all patents granted on these applications.

I authorize and request that the Patent Office officials in the United States and in any and all foreign countries to issue any and all Letters Patent when granted, solely to **FREESCALE SEMICONDUCTOR, INC.**, for its sole use, and that of its successors, assigns, and legal representatives.

I will provide my cooperation to enable the Assignee to enjoy the foregoing right, title, and interest to the fullest extent. Upon request at the expense of the Assignee, I agree to execute all papers, take all rightful oaths, testify in all legal proceedings including patent prosecutorial actions and infringement actions, and do all other such acts which may be necessary, desirable, or convenient for securing and maintaining patents on the foregoing invention or for perfecting title thereto in the Assignee.

I certify that I have the full right to convey the above rights.

25 July 2016
Date

Mitchell Curiel, Assignor
Mitchell Curiel

Date

_____, Assignor
Huan Gim Chan

Date

_____, Assignor
Wan Foong Kho

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Date	Mitchell Curiel	Assignor
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Date	Huan Gim Chan	Assignor
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Date	Wan Foong Kho	Assignor
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_____	_____, Assignor
Date: _____	Mitchell Curiel

_____	_____, Assignor
Date: _____	Huan Jim Chan

_____	_____, Assignor
Date: _____	Wan Foong Kho